

September 1983 Revised April 1999

# MM74HCT14

# **Hex Inverting Schmitt Trigger**

### **General Description**

The MM74HCT14 utilizes advanced silicon-gate CMOS technology to achieve the low power dissipation and high noise immunity of standard CMOS, as well as the capability to drive 10 LS-TTL loads.

The 74HCT logic family is functionally and pinout compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

#### **Features**

- Typical propagation delay: 13 ns
- Wide power supply range: 2-6V
- Low quiescent current: 10 µA maximum
- Low input current: 1 µA maximum
- Fanout of 10 LS-TTL loads
- Typical hysteresis voltage: 0.9V at V<sub>CC</sub> = 4.5V
- TTL, LS pin-out and input threshold compatible

### **Ordering Codes:**

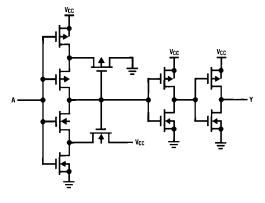
Order Number	Package Number	Package Description		
MM74HCT14M	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-120, 0.150" Narrow		
MM74HCT14SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide		
MM74HCT14MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide		
MM74HCT14N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide		

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### **Connection Diagram**

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## **Schematic Diagram**



## **Absolute Maximum Ratings**(Note 1)

(Note 2)

Supply Voltage ( $V_{CC}$ ) -0.5 to +7.0 V DC Input Voltage ( $V_{IN}$ )  $-1.5 \text{ to } V_{CC} + 1.5 \text{V}$  DC Output Voltage ( $V_{OUT}$ )  $-0.5 \text{ to } V_{CC} + 0.5 \text{V}$  Clamp Diode Current ( $I_{IK}$ ,  $I_{OK}$ )  $\pm 20 \text{ mA}$  DC Output Current, per pin ( $I_{OUT}$ )  $\pm 25 \text{ mA}$  DC V<sub>CC</sub> or GND Current, per pin ( $I_{CC}$ )  $\pm 50 \text{ mA}$  Storage Temperature Range ( $T_{STG}$ )  $-65^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$  Lead Temperature ( $T_{L}$ )

Recommended Operating Conditions

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

(Soldering 10 seconds) 260°C

### **DC Electrical Characteristics** (Note 3)

Symbol	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	Units
Symbol		Conditions		Тур	Guar	anteed Limits	Ollits
$V_{T+}$	Positive Going	Minimum	4.5V	1.5	1.2	1.2	V
	Threshold Voltage		5.5V	1.7	1.4	1.4	V
		Maximum	4.5V	1.5	1.9	1.9	V
			5.5V	1.7	2.1	2.1	V
V <sub>T-</sub>	Negative Going	Minimum	4.5V	0.9	0.5	0.5	V
	Threshold Voltage		5.5V	1.0	0.6	0.6	V
		Maximum	4.5V	0.9	1.2	1.2	V
			5.5V	1.0	1.4	1.4	V
V <sub>H</sub>	Hysteresis Voltage	Minimum	4.5V	0.6	0.4	0.4	V
			5.5V	0.7	0.4	0.4	V
		Maximum	4.5V	0.6	1.4	1.4	V
			5.5V	0.7	1.5	1.5	V
V <sub>OH</sub>	Minimum HIGH Level	$V_{IN} = V_{IL}$					
	Output Voltage	$ I_{OUT}  = 20 \mu A$		$V_{CC}$	V <sub>CC</sub> - 0.1	V <sub>CC</sub> - 0.1	V
		$ I_{OUT}  = 4.0 \text{ mA}, V_{CC} = 4.5 \text{V}$		4.2	3.98	3.84	V
		$ I_{OUT}  = 4.8 \text{ mA}, V_{CC} = 5.5 \text{V}$		5.2	4.98	4.98	V
V <sub>OL</sub>	Maximum LOW Level	$V_{IN} = V_{IH}$					
	Voltage	$ I_{OUT}  = 20 \mu A$		0	0.1	0.1	V
		$ I_{OUT}  = 4.0 \text{ mA}, V_{CC} = 4.5 \text{V}$		0.2	0.26	0.33	V
		$ I_{OUT}  = 4.8 \text{ mA}, V_{CC} = 5.5 \text{V}$		0.2	0.26	0.33	V
I <sub>IN</sub>	Maximum Input Current	$V_{IN} = V_{CC}$ or GND			±0.1	±1.0	μА
		V <sub>IH</sub> or V <sub>IL</sub>			±0.1	±1.0	μΑ
I <sub>CC</sub>	Maximum Quiescent	$V_{IN} = V_{CC}$ or GND	5.5V		1.0	10	^
	Supply Current	$I_{OUT} = 0 \mu A$	5.5V		1.0	10	μА
		V <sub>IN</sub> =2.4V or 0.5V (Note 3)	5.5V		2.4	2.4	mA

Note 3: For a power supply of  $5V \pm 10\%$  the worst case output voltages  $(V_{OH}, \text{ and } V_{OL})$  occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC} = 5.5V$  and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current  $(I_{IN}, I_{CC}, \text{ and } I_{OZ})$  occur for CMOS at the higher voltage and so the 6.0V values should be used.

### **AC Electrical Characteristics**

 $V_{CC} = 5V$ ,  $T_A = 25^{\circ}C$ ,  $C_L = 15$  pF,  $t_r = t_f = 6$  ns

Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay		10	18	ns

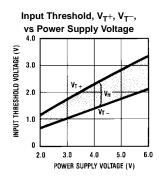
## **AC Electrical Characteristics**

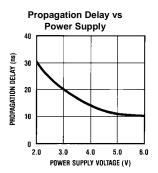
 $\rm V_{CC}\!\!=5V\pm10\%,\,C_L\!=50$  pF,  $\rm t_f\!=t_f\!=\!6$  ns (unless otherwise specified)

Symbol	Parameter	Conditions	T <sub>A</sub> = 25°		T <sub>A</sub> = -40 to 85°C	Units
			Тур	Gua	ranteed Limits	Oilito
t <sub>PHL</sub> , t <sub>PLH</sub>	Maximum Propagation Delay			20	25	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Rise and Fall Time		9	15	19	ns
C <sub>PD</sub>	Power Dissipation	(per gate)		25		pF
	Capacitance (Note 4)					
C <sub>IN</sub>	Maximum Input Capacitance		5	10	10	pF

Note 4:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC} 2 \ f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \ V_{CC} f + I_{CC}$ .

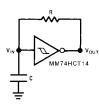
## **Typical Performance Characteristics**





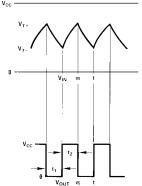
## **Typical Applications**

#### **Low Power Oscillator**

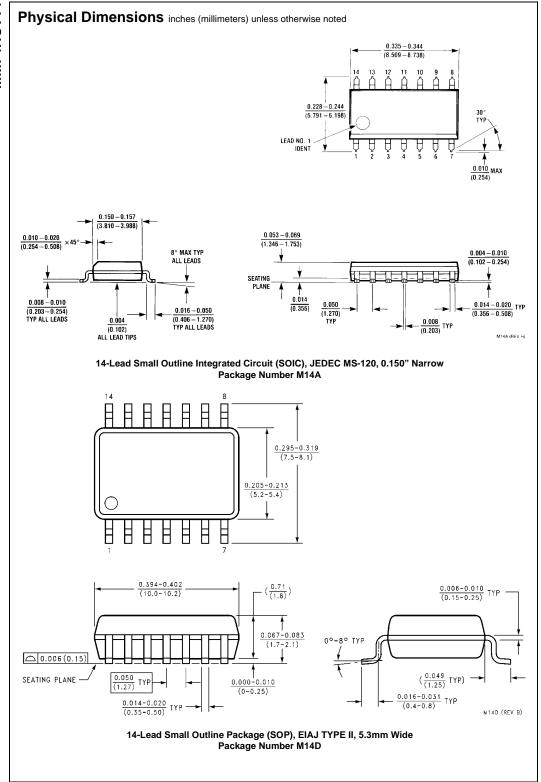


$$t_2\!\approx\!RC\,ln\,\frac{V_{CC}\!-\!V_{T-}}{V_{CC}\!-\!V_{T+}}$$

$$f \approx \frac{1}{RC \ln \frac{V_{T+}(V_{CC} - V_{T-})}{V_{T-}(V_{CC} - V_{T+})}}$$



Note: The equations assume  $t_1+t_2>>t_{pd0}+t_{pd1}$ 



# Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 4LD, TSSOP, JEDEC MO-153, 4.4MM WIDE 5.<u>0±0</u>.1 0.43 TYP -A-7.72 4.16 6.4 4.4±0.1 -B-3.2 -0.42 LAND PATTERN RECOMMENDATION PIN #1 IDENT. SEE DETAIL A ALL LEAD TIPS 0.90+0.15 1.2 MAX -0.09-0.20 L<sub>0.10±0.05</sub> 0.65 . -12.00°TDP & BOTTOM R0.16 R0.31-GAGE PLANE NOTES: 0.25 0°-8° A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ABJREF NOTE 6, DATED 7/93 B. DIMENSIONS ARE IN MILLIMETERS C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS 0.6±0.1 SEATING PLANE -1.00-DETAIL A 14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 0.740 - 0.770 (18.80 - 19.56)0.090 (2.286) 14 13 12 11 10 9 8 14 13 12 INDEX AREA 0.250 ± 0.010 (6.350 ± 0.254) PIN NO. 1 IDENT PIN NO. 1 IDENT 1 2 3 4 5 6 7 1 2 3 $\frac{0.092}{(2.337)}$ DIA $\frac{0.030}{(0.762)}$ MAX OPTION 1 OPTION 02 $\frac{0.135 \pm 0.005}{(3.429 \pm 0.127)}$ 0.300 - 0.320(7.620 - 8.128) 0.065 0.145 - 0.200 0.060 (1.524) 4° TYP Optional (1.651) (3.683 - 5.080)95°±5° $\frac{0.008 - 0.016}{(0.203 - 0.406)}$ TYP 0.020 (0.508)0.125 - 0.150 MIN $\overline{(3.175 - 3.810)}$ $\overline{(1.905 \pm 0.381)}$ (7.112)-MIN 0.014 - 0.023 $\frac{0.100 \pm 0.010}{(2.540 \pm 0.254)} \text{ TYP}$ (0.356 - 0.584) $\frac{0.050 \pm 0.010}{(1.270 - 0.254)} \text{ TYP}$ $0.325 ^{\,+\,0.040}_{\,-\,0.015}$ 8.255 + 1.016

14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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N14A (REV.F)